

IN THE SPECIFICATION:

Please replace the paragraph beginning on page 5, line 11, with the following rewritten paragraph:

Additional leads 106 are preferably disposed on an underside of packaged integrated circuit 100 a short distance from die 102 so that they have the shortest trace length from the integrated circuit device. Additional leads 106 are connected to die 102 in a conventional manner, preferably through wire ~~bonding~~ bonds 112. The shorter the trace length, the lower the lead inductance, and the higher the speed that may be achieved at additional leads 106. In the present embodiment, four additional leads 106 are disposed on a single side of die 102. However, any number of additional leads 106 may be disposed on any or all of the sides of die 102. Further, while it is preferable for additional leads 106 to be disposed adjacent to die 102, they may be disposed anywhere on the underside of packaged integrated circuit 100. However, the shortest distance from die 102 is most preferable due to the reasons specified above.